

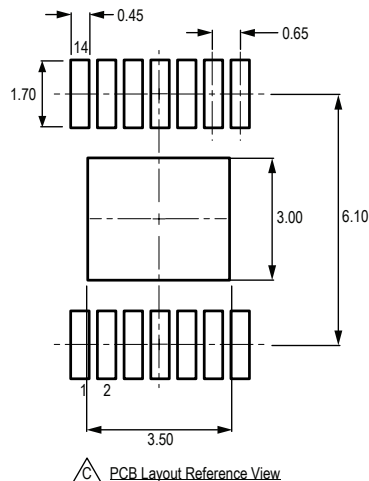
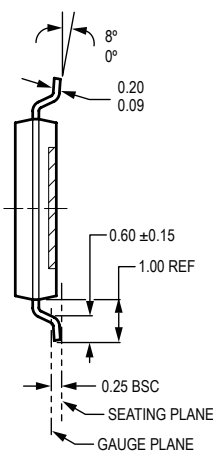
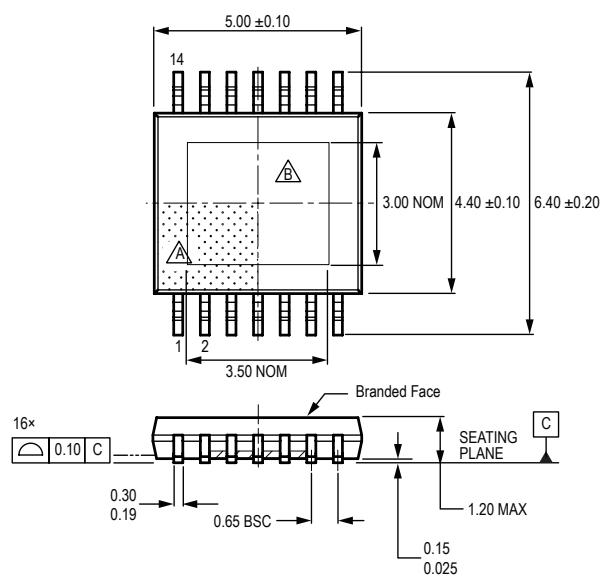
For Reference Only – Not for Tooling Use

(Reference MO-153 ABT-1; DWG-0000379, Rev. 3)

Dimensions in millimeters – NOT TO SCALE

Dimensions exclusive of mold flash, gate burrs, and dambar protrusions

Exact case and lead configuration at supplier discretion within limits shown



△ Terminal #1 mark area

△ Exposed thermal pad (bottom surface)

△ Reference land pattern layout (reference IPC7351 SOP65P640X110-15M); All pads a minimum of 0.20 mm from all adjacent pads; adjust as necessary to meet application process requirements and PCB layout tolerances; when mounting on a multilayer PCB, thermal vias at the exposed thermal pad land can improve thermal dissipation (reference EIA/JEDEC Standard JESD51-5)

△ Standard Branding Reference View

Line 1, 2 = 7 characters
Line 3 = 5 characters

Line 1: Part Number
Line 2: Logo A, 4 digit Date Code
Line 3: Characters 5, 6, 7, 8 of Assembly Lot Number